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Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number. Application Number 09/871,383 Filing Date TRANSMITTAL 05.31.2001 FORM First Named Inventor Edlin Solomon Art Unit (to be used for all correspondence after initial filing) Joseph Nguyen Examiner Name Attorney Docket Number 58 Total Number of Pages in This Submission **ENCLOSURES** (Check all that apply) After Allowance communication Fee Transmittal Form Drawing(s) to Technology Center (TC) Appeal Communication to Board Licensing-related Papers Fee Attached of Appeals and Interferences Appeal Communication to TC + (Appeal Notice, Brief, Reply Brief) Amendment/Reply Petition to Convert to a Proprietary Information After Final Provisional Application Power of Attorney, Revocation Status Letter Affidavits/declaration(s) Change of Correspondence Address Other Enclosure(s) (please Terminal Disclaimer Extension of Time Request Identify below): Request for Refund **Express Abandonment Request** CD, Number of CD(s) Information Disclosure Statement Remarks Certified Copy of Priority Document(s) Response to Missing Parts/ Incomplete Application Response to Missing Parts under 37 CFR 1.52 or 1.53 SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT Firm Edlin Solomon Individual name Signature Date 07.15.2004 CERTIFICATE OF TRANSMISSION/MAILING I hereby certify that this correspondence is being facsimile transmitted to the USPTO or deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date shown below. express mail Typed or printed name Edlin Solomon

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Examiner – Joseph Nguyen Applicant – Edlin Solomon Reply mailed 07.15.2004.

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Reply mailed 07.15.2004. **JUL 2 1** 2004 Application 09/871,383(20020089000-A1). Art unit 2815. Mailing date 9.27.2002 **CF Part OF S**

Reply No.10 to Notice received on 10.18.2002.

H01L 29/06 H01L 29/70

BIDIRECTIONAL BIPOLAR STATIC INDUCTION DEVICE

"paragraph 0001". The invention relates to microelectronics and more particularly to bidirectional bipolar static induction devices: transistor and transistor-thyristor (transistor, which can be latched) with elements of a control circuit. Any device, according to the present invention can be latched. However, if a thick channel drain electrode have been connected to an ordinary channel drain electrode and if the latch current of the device exceeds the maximum permissible current, such device can be considered as the device without latching, i.e. the transistor.

background of the invention

"between paragraph 0001 and 0002". There exists a static induction type semiconductor device is used as a power transistor. It is of the surface gate type and is used for providing a high current density. The static induction type semiconductor device provides a plurality of a small source regions surrounded by a gate region. According to this structure the channel region beneath the source region becomes small, thereby increasing the stored carrier density and enabling a large main current to flow when using a small gate current, thereby achieving a high current amplification ratio. A thin insulating film provided on the surface of the n+-source region operates as a tunnel-oxidized film, thereby enabling electrons to be injected into the source region but preventing the positive holes from being drawn out. Therefore, as the consumption of positive holes store in the channel region decreases, a sufficiently large source current is allowed to flow even if a further smaller gate current is injected, thereby further increasing the current amplification factor[1]. The drawbacks of the transistor are that it cannot operate on circuits of alternating voltage and that the current density is insufficient.

There exists a vertical JFET, in which a gate and a channel are formed by the implantation of an impurity in a doped epitaxial layer through mask — a doped polysilicon source electrode[2]. The method provides forming of the transistor with channel thickness equal about 10.sup.-7 m. The drawback of the transistor is that it cannot operate on alternating voltage circuits.

"paragraph 0002". There exists a bipolar static induction transistor comprising elements of a bipolar static induction transistor: a gate, a source and a channel – on one of the sides of the substrate, and elements of a onejunction transistor: an emitter and a base (drain) – on the other [3]. This transistor has high current density and can switch high power. The drawback of the transistor is that it cannot operate on circuits of alternating voltage (to be more precise, it can be closed by applying only one of polarities of the drain-source voltage).

"paragraph 0003". There exists a bipolar transistor, which has structure actually comprising two bipolar transistors and which can operate in alternating-voltage circuit [4]. The drawback of the transistor is that it cannot has high technical characteristics. Its breakdown voltage, current density and switch power are low.